

IN THE SPECIFICATION:

Kindly add the following paragraph after paragraph 0011 on page 3:

[0011.1] Figure 6 shows an alternative embodiment of an integrated chip package in accordance with the principles of the invention.

Kindly add the following paragraph after paragraph 0022 on page 10:

[0022.1] Referring to Figure 6, an alternative embodiment of an integrated chip package 600 in accordance with the principles of the invention is shown. According to the alternative exemplary embodiment, the heat sink 22 is substantially thermally isolated from the package substrate 26. For purposes of illustration and not limitation, thermal isolation members 605 can be used to thermally isolate the heat sink 22 from the package substrate 26. Each of the thermal isolation members 605 can be made of any suitable material that is capable of thermally isolating the heat sink 22 from the package substrate 26 or otherwise substantially blocking or preventing the transfer of heat from the heat sink to the package substrate 26.